

TFSP - 840 Sputtering System



- New generation Magnetron Sputtering Deposition system
- Especially tailored for R&D, pilot production and research
- Compact construction, small footprint ideal for clean room
- Fully Automatic Control PC/PLC
- Human Machine Interface software
- Process recipes builder with PC backup and Windows features
- Historical data records
- Fully adaptable to a wide range of processes
- Range of optional devices including gun size, power supplies and more
- Substrate load lock for fast pump down cycle, optional

Taylor your system for your application

Technical Data:

Vacuum Chamber:	Stainless Steel box with full opening front door and 4" view port
Vacuum System:	Turbomolecular or cryogenics high vacuum pump, dry scroll or oil rotary pump and all necessary valves and fittings to achieve 10^{-7} Torr vacuum
Vacuum Measurements:	Full range vacuum gauge + BARATRON® for gas control
Substrate Stage:	Rotated up to 6" diameter
Source:	One or multiple magnetron guns
Power Supply:	RF, DC or DC pulsed
Gas Inlet:	1-4 channels with MFC & bellow sealed stainless steel shutoff valve
Automatic Control:	PC / PLC



Optional Devices:

- Griddless / gridded ion source
- Isolated stage with etching and cleaning capabilities
- Quartz crystal rate/thickness monitor with deposition rate controller
- Load lock for 3" sample
- Quartz lamp heater
- Adjustable height of sample holder
- Step positioned substrate stage

Contact



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